November 20, 2025

89th Issuance of Domestic Unsecured Straight Bonds

ACOM CO., LTD. has reached a decision to make its 89th issuance of domestic unsecured straight bonds, as outlined below. The funds procured through this issuance will be used for partial repayment of long-term borrowings.

Name of issuance	ACOM CO., LTD. 89th issuance of domestic unsecured straight bonds
Total value	20 billion yen
Interest rate	1.532% annually
Individual bond value	100 million yen
Issue price	Face value 100 yen
Redemption price	Face value 100 yen
Application period	November 20, 2025
Payment date	November 27, 2025
Maturation date	November 27, 2028
Application of funds procured	Partial repayment of long-term borrowings
Trustee	Mitsubishi UFJ Morgan Stanley Securities Co., Ltd. SMBC Nikko Securities Inc. Daiwa Securities Co. Ltd. Nomura Securities Co., Ltd.
Transfer agent	MUFG Bank, Ltd.
Credit ratings	Rating and Investment Information, Inc.: AA- Japan Credit Rating Agency, Ltd.: AA-

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